IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

3/1/00

In re the Application of:

Masayuki Yasuda

Serial No.: 09/019,087

Filed: 2/05/98



TIJ-24816

Art Unit: 1765

For: MANUFACTURING METHOD OF SEMICONDUCTOR IC DEVICE

REQUEST FOR RECONSIDERATION

02/23/00

Assistant Commissioner for Patents

Box A.F.

Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R.

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Ass't Commissioner for Patents, Box A.F., D.C. 20231 on Fébruary 23, 2000.

William B. Kempler, (Reg. No. 28,228

Applicant requests reconsideration of Claims 1-11 which were rejected by the examiner under 35 U.S.C. Section 103 (A) as being unpatentable over Tsuji '625.

In paragraph 2 of the official action, the examiner states:

"...which is followed by the formation of trenches on said insulating film..." (emphasis added).

On the last line of page 2, the examiner states that:

"...nor does he disclose the trenches having sidewalls."